



Product Change Notification

108764 - 03

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108764 - 03
Change Title: Intel(R) IP Network Server NSC2U, PCN 108764-03, Product Design, Fab Spin to Improve CPU FSB Routing, Reason for Revision: Adding information about heat sink change
Date of Publication: January 13, 2009

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 26, 2008
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Description of Change to the Customer:

Reason for Revision: Adding information about heat sink change

Intel is implementing a printed circuit board (PCB) change to improve the Front Side Bus (FSB) routing for the secondary processor. This design change will result in better signal quality.

Intel is changing the Processor1/Processor2 Voltage Regulator heat sink on the Intel(R) Server Board S5000PAL from a non-anodized to anodized version. This heat sink is approximately 161mm long, 10.67mm wide, and 15.5mm high and comes attached to the server board on top of the Processor1/Processor2 Voltage Regulator (VR) Field Effect Transistors (FETs). The anodized version of the heat sink is black in appearance and has improved thermal conductivity and electrical insulation characteristics. The part number for the VR Heat sink is changing from Intel part number D17794-001 to D57771-003.

Customer Impact of Change and Recommended Action:

No customer impact is being projected.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
NSCD0202W	900074	E49436-005	D78511-204	E49436-006	D78511-300
NSCA0202W	900075	E49435-005	D78511-204	E49435-006	D78511-300
NSCSASBSBDW	889828	D89061-005	D78511-204	D89061-006	D78511-300

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 27, 2008	00	Originally Published PCN
August 28, 2008	01	Correct milestone date
December 3, 2008	02	Add TA & PBA revision
January 13, 2009	03	Adding information about heat sink change